PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCI No.	ADG/22/13500
1.3 Title of PCI	Test pattern relocation from inner dice to scribing line
1.4 Product Category	SiC
1.5 Issue date	2022-06-15

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Maurizio Maria FERRARA
2.1.2 Marketing Manager	Michele MACAUDA,Marcello SGROI
2.1.3 Quality Manager	Vincenzo MILITANO

3. Change

3.1 Category	**3.2 Type of change**	**3.3 Manufacturing Location**
Wafer Fab (Process)	Mask Frame : introduction of new structure or never tested structure, change of die scribe separation or scribe line width	Shenzhen

4. Description of change

	Old	**New**
4.1 Description	For each litho mask step a die is sacrified for test pattern structure	Moving the test pattern structures to the scribe line will increase the wafer gross
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact	

5. Reason / motivation for change

5.1 Motivation	To grant a better service continuity
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	by new FG

7. Timing / schedule

7.1 Date of qualification results	2022-06-09
7.2 Intended start of delivery	2022-06-30
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	**Issue Date**	

9. Attachments (additional documentations)

13500 Public product.pdf
13500 PCI TEG GEN1 and GEN2.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	SCT1000N170	
	SCT10N120	
	SCT10N120AG	
	SCT20N120	
	SCT20N120AG	
	SCT20N120H	
	SCT30N120	
	SCT30N120H	
	SCT50N120	
	SCTH100N65G2-7AG	
	SCTH35N65G2V-7	
	SCTH35N65G2V-7AG	
	SCTH40N120G2V-7	
	SCTH40N120G2V7AG	
	SCTH70N120G2V-7	
	SCTH90N65G2V-7	
	SCTW100N65G2AG	
	SCTW35N65G2V	
	SCTW35N65G2VAG	
	SCTW40N120G2V	
	SCTW40N120G2VAG	
	SCTW70N120G2V	
	SCTW90N65G2V	

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Automotive Discrete Group (ADG)
Power Transistor Division

CUSTOMER NOTIFICATION

Test pattern relocation from inner dice to scribing line

INVOLVED PRODUCT: **All SiC GEN1 & GEN2 produced in Shenzhen plant**

Dear Customer,

Following the continuous effort to grant a better service continuity, we would like to inform you about the relocation of Test pattern structures from inner dice to the scribe line

In the next pages, we are reported all the details of the change and the plan to release it in production.

Sincerely Yours!

Tech name	
ST Part number:	ST PN: **SCT30N120 SCT30N120H SCT20N120 SCT20N120H SCT20N120AG SCT50N120 SCTH50N120-7 SCT10N120 SCT10N120H SCT10N120AG SCT20N170 SCT20N170AG SCT1000N170 SCTH1000N170 SCT1000N170AG SCTH1000N170AG SCT35N65G2D7 SCTF35N65G2 SCTH35N65G2V-7 SCTW35N65G2V SCTH35N65G2V-7AG SCTH35N65G2V7SAG SCTHU35N65G2-AG SCTW35N65G2VAG SCTH90N65G2V-7 SCTW90N65G2V SCT100N65G2D8AG SCTH100N65G2-7AG SCTW100N65G2AG SCTH40N120G2V-7 SCTW40N120G2V SCT60N120G2D7 SCTH60N120G2-7 SCTW60N120G2 SCTH70N120G2V-7 SCTW70N120G2V SCT40N120G2VD8AG SCTH40N120G2V7AG SCTW40N120G2VAG SCTH60N120G2-7AG SCTHU60N120G2AG SCTW60N120G2AG SCTH100N120G2-AG SCTHU100N120G2AG SCTW100N120G2AG** Package: Hip247 H2pak
Reason and background of the change	To grant a better service continuity while increasing the dice quantity per wafer
Detailed description of change(s), including affected type of changes	Relocating the test pattern structures from inner wafer to scribe line allows a wafer gross increase
Impact on form, fit, function, or reliability.	NA
Datasheet	NA
Benefit of the change	To grant a better service continuity
Qualification Plan and Implementation date for change	Assy Workability
Traceability Information	Dedicated FG
PPAP Update	NA

Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCI Title : Test pattern relocation from inner dice to scribing line

PCI Reference : ADG/22/13500

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

SCTW40N120G2VAG	SCTW100N120G2AG	SCTW40N120G2V
SCTW60N120G2	SCT10N120	SCT10N120AG
SCT30N120	SCT20N170AG	SCT50N120
SCTH70N120G2V-7	SCTH35N65G2V-7	SCTH60N120G2-7AG
SCTW60N120G2AG	SCTW35N65G2VAG	SCTH100N65G2-7AG
SCT1000N170	SCTW90N65G2V	SCT20N120H
SCTW35N65G2V	SCTH35N65G2V-7AG	SCT20N170
SCT30N120H	SCT20N120	SCT20N120AG
SCTH40N120G2V-7	SCTH90N65G2V-7	SCTW70N120G2V
SCTH40N120G2V7AG	SCT1000N170AG	SCTH60N120G2-7
SCTW100N65G2AG		

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